



产品承认书

PRODUCT APPROVAL

Client Name :

客户名称 : _____

Client P/N :

客户品号 : _____

Product P/N :

产品型号 : **GFJ-C3234W-60W-150B10C6 (T60灯)**

Date:

日期 : _____

Client approval 客户审核		GaoFeiJie approval 高飞捷审核		
Approval 核准	Audit 确认	Approval 核准	Audit 确认	Confirmation 制作
				魏浩齐
<input type="checkbox"/> Qualified 接受	<input type="checkbox"/> Disqualified 不接受	DATE: 日期:		

Factory : A building, Baiyang industrial area, KengWei Road, Shiyantown
Bao'an District, Shenzhen, Guangdong

地址 : 中国 广东省 深圳市 宝安区石岩坑尾大道百阳工业区A栋

Tel/电话 : 0755-29767696

Fax/传真 : 0755-29580131

Web/网址 : www.gfj918.com

注: 1.此规格书以中英文方式书写,若有冲突以中文版本为准文本.

2.此规格书的最终解释权归深圳高飞捷科技有限公司.

3.此规格书的有效期限为两年,自盖章或签字之日起计算.

4.为提高产品性能,或市场原订品牌材料供应短缺,更换其他材料品牌,不再另行通知.



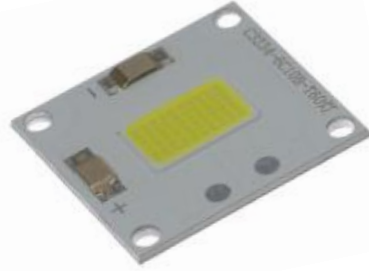
Volume production	
Research and development	◆

1.Part code 产品型号命名原则

C 3234 W - 60W -150 B10 C6

① ② ③ ④ ⑤ ⑥ ⑦

- ① Product line code 产品系列代码
- ② Product code base plate 产品基板代码
- ③ Emitting light colors 发光颜色
- ④ Recommend the minimum Power
建议使用的最大功率
- ⑤ Luminous flux 光通量
- ⑥ The number of parallel Circuit 并联电路数
- ⑦ The number of series Circuit 串联电路数



ATTENTION注意
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES
请勿裸手接触器件

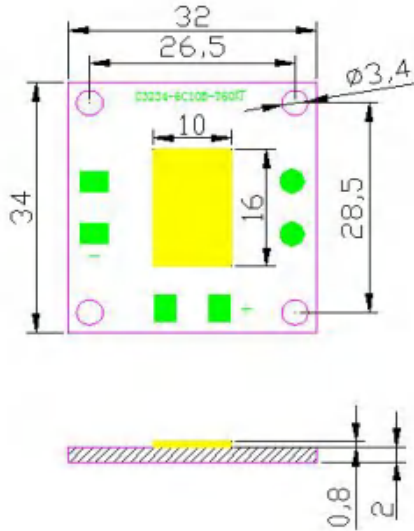
2.Features 特点

- Dimension 32mm×34mm×2mm
尺寸 32mm×34mm×2mm
- CRI: -- 显色指数：--
- Wide viewing angle : 160° 发光角度：160°
- RoHS compliant (ROHS标准)
- Sulphation corrosion resistance 抗硫化
- Manual Soldering 手工焊接
- Flip chip technology, no dead lights risk 倒装芯片工艺、无死灯风险
Higher temperature carrying capacity, higher physical strength, higher reliability and longer service life.
更高温度的承载能力，更高的物理强度，更高的可靠性，更长的使用寿命
- Higher optical efficiency and low temperature process encapsulation
更高光效、低温工艺封装
Excellent concentrating performance, reduce light loss, improve light efficiency and send light effect.
聚光性能极佳，减少了光的损失，提升了出光效率、寄光效果
Good temperature resistance and longer life.
耐高温性能良好，寿命更长
- The superconducting aluminum substrate is used as the heat conduction carrier.
采用超导铝材质基板作为导热载体
Low thermal resistance and better heat dissipation performance
低热阻，兼具更好散热性能

3.Applications 应用

- Projection lamp 投影灯

4.Package Dimensions 封装尺寸



- 1、 All dimensions are in millimeters(inches);
所以尺寸以mm为单位 (inches)
- 2、 Tolerance unless otherwise specified: $\pm 0.3\text{mm}$.
尺寸公差为 ± 0.3 毫米除非另有说明

5.Performance 性能

(1) Absolute Maximum Ratings 绝对最大额定值

Parameter参数	Symbol符号	Min.	Typ.	Max.	Units单位
Input power range 输入功率范围	Pi	54	60	70	W
operating current range 工作电流范围	IF	2800	3200	3600	mA
Parameter参数	Symbol符号	Rating Value值			Units单位
Junction Temperature结温	Tj	115			°C
Operating Temperature Range工作温度	Top	-35°C To +90°C			
Storage Temperature Range储藏温度	Tstg	-40°C To +100°C			
Lead Soldering Temperature*引线焊接温度	T _{SOL}	Max. 350°C for 5sec Max.			

Notes for Table:

1.The temperature of Aluminum PCB do not exceed **90°C**. If the input power reach 80% max Pi, the temperature of Aluminum PCB should be control below **80°C**

基板负极引线温度不能超过**90°C**。如果输入功率达到最大输入功率的**80%**以上,基板负极引线温度应控制在**80°C**以内。

2.When hand soldering, keep the temperature of iron below less **460°C less than 5seconds**

当手工焊接时,烙铁的温度必须**小于460°C**,时间**不能超过5秒**

3.D.C. Current : $T_j = T_s + R_j \cdot I_s \times P_i$

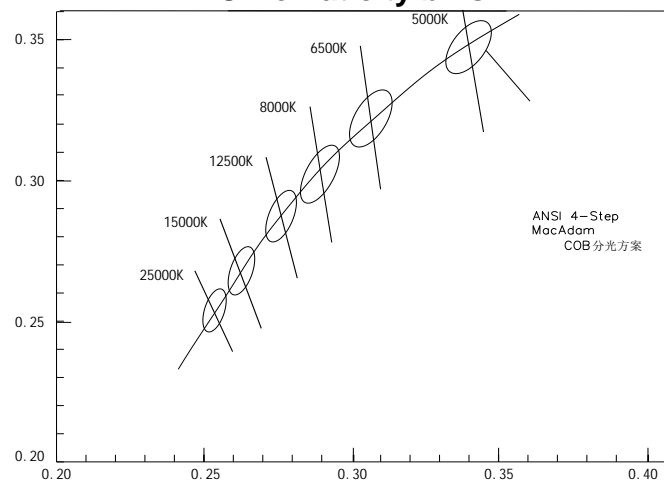
(2) Electro-Optical Characteristics at Tc=25°C

光电特性 Tc=25°C

Parameter参数	Symbol符号	Condition 条件	Min.	Typ.	Max.	LM/W (typ)	Unit 单位
Forward Voltage 正向电压	VF	IF=3100mA	17	18	19	--	V
Luminous Flux 光通量	Φv	TC=10000K	8586	9072	9558	162	Lm
		TC=13000K	8427	8904	9381	159	
		TC=16000K	8321	8792	9263	157	
		TC=19000K	8109	8568	9027	153	
		TC=21000K	8003	8456	8909	151	
		TC=25000K	7738	8176	8614	146	
		--	--	--	--	--	
CRI 显色指数	Ra	IF=3100mA	--	--	--	--	--
Thermal Resistance 热阻	R (j-s)	IF=3100mA	--	0.27	--	--	°C/W

6.Product bins 产品分级

Chromaticity bins



Center TC	5025K	6545K	8085K	12528K	15125K	25030K
X,Y	0.3430,0.3505	0.3132,0.3233	0.2946,0.3043	0.2701,0.2752	0.2631,0.2668	0.2524,0.2536

Notes for Table

*1.Color bins are defined at IF=3100mA operation. If use different forward current, it will cause the change of chroma-ticity and forward voltage.

该产品通过瞬态3100mA 点亮, 分光分色. 若使用不同电流, 会引起色温及电压的变化

*2.The tolerance of measurement at our tester is VF+/-3% , Φv+/-10% and Ra+/-2.

测试仪测量的公差在电压±3%, 流明±10% 和显指±2。

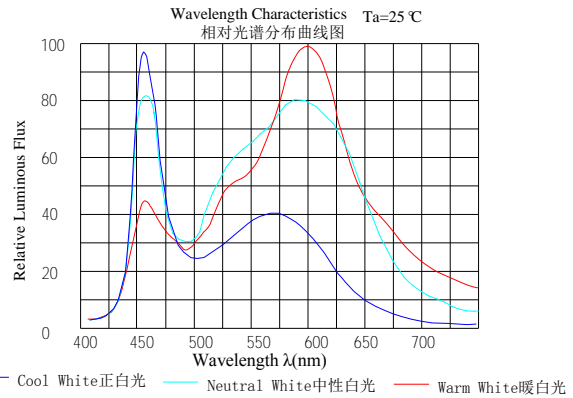
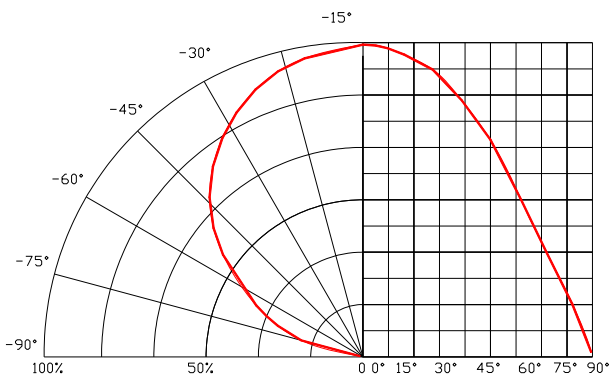
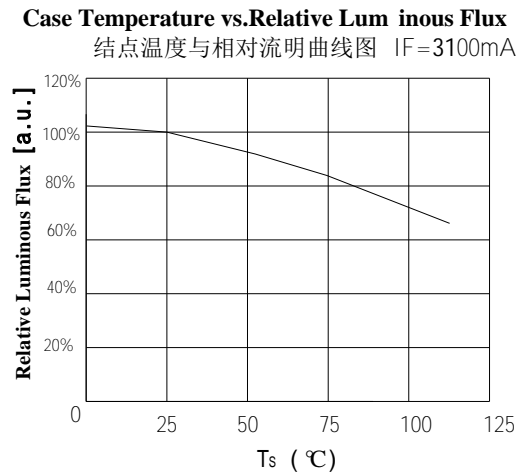
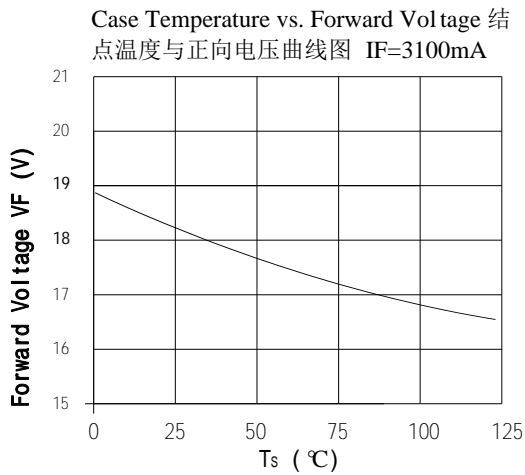
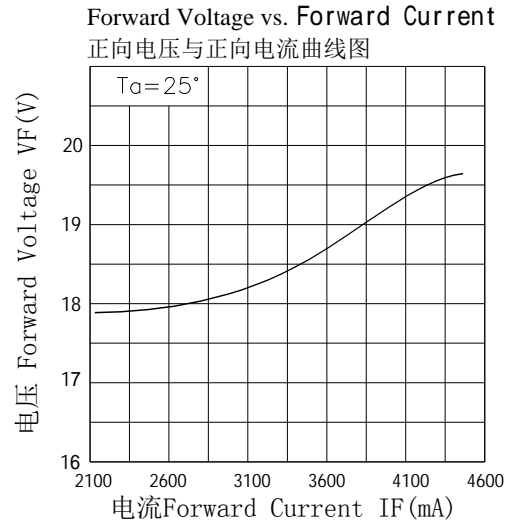
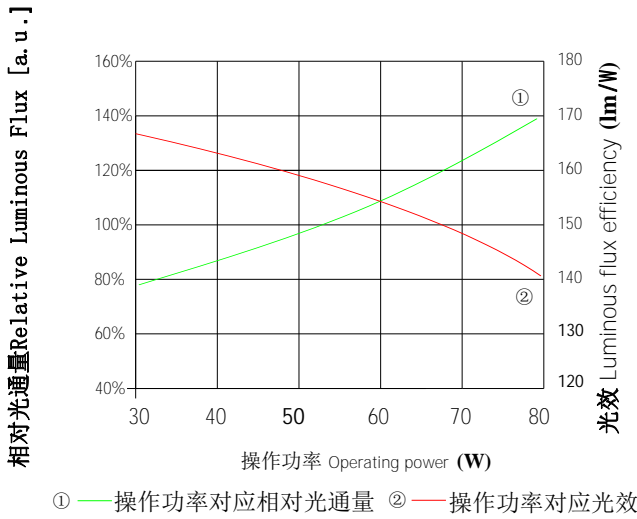
3.Tolerance of ±0.005 on x,y coordinates.

色坐标的测量误差允许在±0.005

4.Color region stay within MacAdam "4-step" ellipse from the chromaticity center. The chromaticity center refers to ANSI C78.377-2008.

色域可控制在色温中心坐标的4阶麦克亚当椭圆之内, 色温分bin参考ANSI C78.377-2008。

7.Characteristics特性



Volume production	
Research and development	◆

8.Packing Specifications 包装规格






型号 (Type) : _____

电压 (VF) : _____ 电流 (IF) : _____

色温 (TC) : _____ 光效 (LMW) : _____

显指 (Ra) : _____ 数量 (QTY) : _____


 20180101-05

Label on ESD shielding 静电袋上标签






品名 (Description) : _____

产品型号 (Type) : _____

发光颜色 (Color) : _____

数量 (QTY) : _____

出货日期 (Date) : _____

Label on box 外箱标签

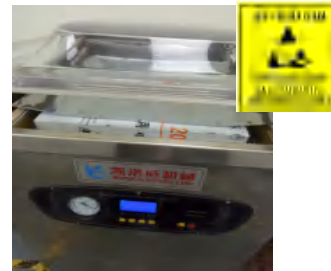
IF: Rated working current 额定工作电流
 VF: Forward voltage rank 正向电压档次范围
 ΦV: Luminous Flux rank 光通量档次范围
 TC: Color temperature 色温

■ Packing figure 包装图

- ▶ Quality and safety 质量 + 安全
- ▶ Anti shock resistance 色泽均匀|抗冲击|防震|防压|防潮|耐磨



出货外形包装
Outer box packing



真空静电包装
Vacuum electrostatic packaging



优质泡沫
High quality foam

Volume production	
Research and development	◆

Precaution for use (防护措施)

1. Storage 储存

To avoid moisture, we recommend storage conditions for the unopened LED +5 ~ +30 °C, relative humidity <60%. LED should be used within 168 Hrs. of opening the package. Please make sure to dehumidify and vacuum pack the remaining/ unused LED. Dehumidifying condition: +120 °C ±5 °C, 04 Hrs. Effective age for the sealed led is one year. 为避免受潮的影响，我司建议产品在未开包装前储存条件为 5-30° C，相对湿度小于 60%。已开包装的 LED 光源请在 168H 内使用安装完毕，如未用完之产品，请进行除湿并抽真空后密封保存。除湿条件：120° C±5° C，4H。产品密封保存有效使用期为一年。

2. The soldering precautions 组装注意事项：

Soldering conditions: Reflow soldering is not recommended for this LED. If hand soldering, set soldering iron temperature at 460 °C and soldering time not More than 5 seconds, after the first soldering, make sure the substrate surface temperature returns to ambient temperature before a second soldering. Please make sure when soldering, there is no external force on the soldering surface and silicon batardeau (such as pressure, friction or sharp metal nails, etc.), to avoid colloid rupture or damage chip and other abnormalities. If beyond recommended conditions, we cannot guarantee the LED stability, please do the risk assessment first.

During assembly, please ensure that a good quality thermal paste is applied and distributed evenly over the surface. While using thermal pad (Heat Sink), make sure LED is firmly tightened and there is no gap between surfaces. In such heat-media products, through a pressure test of at least 500 volts. 焊接条件：此产品不推荐使用回流焊接的作业方式，手工焊接烙铁温度设定 460° C，焊接时间不可超过 5 秒，第一焊点焊接后请确保基板表面温度恢复到环境温度，方可进行第二次的焊接。焊接时请注意不可有外力作用于胶体表面及外圈的围堰胶上（如压力，摩擦或锋利金属钉等），以免造成胶体破裂或损伤芯片等异常；如果超出此使用条件，高飞捷将不能保证产品的稳定性，如需使用超出的操作条件，请务必进行风险评。

为确保在组装时降低接触热阻，请注意导热膏涂布均匀且分布面积合理，不可出现导热膏太少或涂抹高低不平等现象。如使用导热胶垫时，请确保螺丝安装后基板与导热胶垫的完全接触，不可存在中空现象。产品在此类耐热介质下，能通过至少1500伏的耐压测试。

3. Anti-Static Measures 防静电措施：

Please take adequate measures to prevent electrostatic generation, such as wearing electrostatic ring or anti-static fingerstall etc; any relative products like plant equipment, machinery, carrier and transportation units shall be connected to discharging unit/ ground. The ESD sensitivity of this product is > 1000V(HBM), after assembly the final lamp, please make sure to discharge Static Electricity by proper ESD equipment. 请采取足够的措施来防止静电产生，比如带静电环或防静电手指套等；每个制造厂关于产品（工厂、设备、机器、载波机和运输单位）应当连接到底面，请避免产品电气带电；本产品的防静电敏感度超过1000V(HBM)，装配后的最终灯具产品（S）建议检查是否损坏LED（漏电现象）。

Volume production	
Research and development	◆

4. Temperature Control 温度控制：

Recommended temperature conditions for enhanced product life: Be sure to TS point (negative pads) controlled below 90 °C, COB products use power 20W or less, it is recommended to control the colloid surface temperature ≤ 160 °C. COB product use of power between 30-50W, colloid surface temperature control is recommended ≤ 180 °C. COB product use of power between 60-160W, colloid surface temperature control is recommended ≤ 200 °C.

保证散热前提条件为：请务必将TS点（负极焊盘）控制在90℃以下，如COB产品使用功率在20W以下，其建议控制胶体表面温度在 ≤ 160 ℃，如COB产品使用功率在30W-50W以内，建议控制胶体表面温度在 ≤ 180 ℃，如COB产品使用功率在60W-160W以内，建议COB胶体表面温度控制 ≤ 200 ℃。

5. The drive control 驱动控制：

Drive this product at constant current. Output current range specifications should be according to the operational and other conditions, as mentioned in data sheet. Before using a constant voltage source or altered specifications other than recommended, please consider risk factors.

本产品需使用恒流源进行驱动，且输出电流符合规格书上的功率使用范围，如需使用恒压源或其他使用条件，请进行使用效果风险评估。

6. Other 其他：

Should the product be used outdoors, be sure to IP (protection class) ≥ 65

若本产品户外使用，请务必将IP(防护等级) ≥ 65

Product is not suitable to use in following conditions

本产品不可在以下条件下使用，如果产品在以下条件下使用，评估其使用效果和风险是有必要的：

- Direct or indirect wet / damp conditions, such as rain, etc.;
- 直接或间接的打湿或受潮，比如淋雨等；
- In contact with sea water and erosive materials
- 被海水损害或侵蚀；
- Exposed to corrosive gases (e.g., Cl₂, H₂S, NH₃, SO_x, NO_x, etc.);
- 被暴露于腐蚀性气体(如 Cl₂, H₂S、NH₃、SO_x、NO_x等)；
- Exposed to dust, liquids or oils.
- 被暴露于粉尘、液体或油。



OK



NG